Ultar-low Power High Performance 2.4 GHz GFSK Tranmitter

Key Features

- 2.4GHz ISM band operation
- Built-in 64 programmable NVM memory
- Ultra-low power consumption automatic transmission function
- Low voltage automatic alarm function
- Integrated temperature alarm function
- Integrated NTC temperature acquisition function
- Border count function
- BLE4.2 broadcast package transmission function
- Tamper alarm function
- Integrated conflict prevention communication mechanism
- Built-in 3KHz RCOSC and Hardware Watchdog
- 3.3V programming voltage
- Modulation: GFSK
- Data rate: 2Mbps/1Mbps/250Kbps
- Ultra low shutdown current: 1.0uA

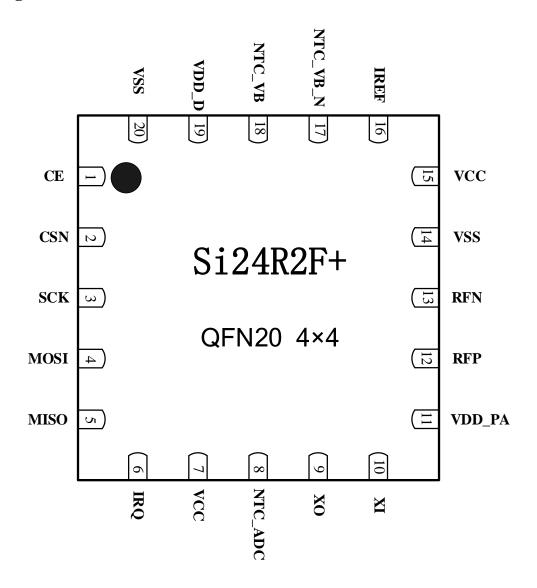
- Wide supply range: 2.1-3.6V
- Wide digital I/O voltage range: 1.9-3.6V
- Crystal: 16MHz±10ppm
- Maximum transmission power: 12dBm
- TX supply current (2Mbps): 20mA (1dBm)
- Maximum 10MHz, 4-wire SPI
- Transmit data hardware interrupt output
- QFN20 package
- Compatible with Si24R1 and Si24R2 transmission function

Applications

- ◆ Ultra low power active RFID system
- ♦ Smart campus card management system
- ◆ Electric bicycle anti-theft system
- ◆ Fixed assets regulatory system
- ◆ The intelligent animal shepherd system

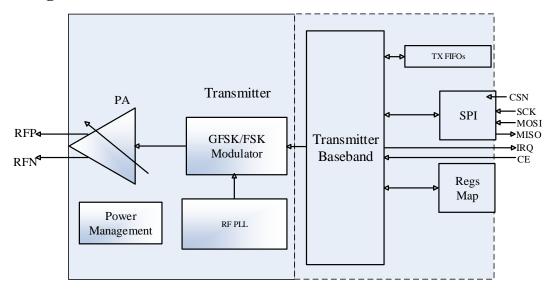


Pin Assignments





Block diagram



Abbreviations

ARQ	Auto Repeat-reQuest		
ART	Auto ReTransmission		
ARD	Auto Retransmission Delay		
ATR	Auto Transmission		
BER	Bit Error Rate		
CE	Chip Enable		
CRC	Cyclic Redundancy Check		
CSN	Chip Select		
DPL	Dynamic Payload Length		
GFSK	Gaussian Frequency Shift Keying		
IRQ	Interrupt Request		
ISM	Industrial-Scientific-Medical		
LSB	Least Significant Bit		
Mbps	Megabit per second		
MCU	Micro Controller Unit		
MHz	Mega Hertz		
MISO	Master In Slave Out		
MOSI	Master Out Slave In		
MSB	Most Significant Bit		
NVM	Non-volatile Memory		



PA	Power Amplifier	
PID	Packet Identity	
PLD	Payload	
RX	RX	
TX	TX	
PWR_DWN	Power Down	
PWR_UP	Power UP	
RF_CH	Radio Frequency Channel	
RSSI	Received Signal Strength Indicator	
RX	Receiver	
RX_DR	Receive Data Ready	
SCK	SPI Clock	
SPI	Serial Peripheral Interface	
TX	Transmitter	
TX_DS	Transmit Data Sent	
XTAL	Crystal	
Watchdog	Hardware Watchdog	



Contents

1 Introduction	7
2 Pin Information	9
3 Operational modes	11
3.1 State Control Diagram	11
3.1.1 Shutdown Mode	11
3.1.2 Standby Mode	12
3.1.3 Idle-TX Mode	12
3.1.4 TX Mode	12
3.1.5 ATR Mode	12
4 Packet processing protocol	14
4.1 Packet format	14
4.2 Communication Mode	15
4.2.1 NO ACK Mode	15
4.2.2 Dynamic payload length (DPL) and static payload length	15
4.3 Compatibility Mode	15
4.4 Bluetooth Mode	16
5 SPI Interface	17
5.1 SPI Commands	17
5.2 SPI Timing	18
6 Register Table	20
7 Electrical specification	24
7.1 Limitation parameter	24
7.2 Electrical specification	24
8 Package	26
9 Typical Application Schematic	29
9.1 Typical Application Schematic	29
9.2 PCB layout	30
10 Version Information	32



11 Order Information	. 33
12 Technical Support and Contact Information	34
Annendiy - Ton machine screenshot	35



1 Introduction

Si24R2F+ is a wireless transmission chip with embedded transmission baseband, operating in the 2.4GHz ISM frequency band, suitable for ultra-low power wireless applications. The operating frequency band from 2400MHz to 2525MHz is divided into 126 RF channels.

Si24R2F+ uses GFSK/FSK digital modulation and demodulation. Both air data rate and PA output power are configurable. The air data rate can be programmed to 2Mbps, 1Mbps and 250Kbps. The higher data rate contributes the lower power consumption because it takes less time to transmit or receive signals.

Si24R2F+ is especially optimized for low power applications. All the register values and FIFO values are maintained in Shutdown mode and the shutdown supply current is 1uA. In Standby mode, the clock still works and the standby supply current is 15uA. It takes less than 130us to start data transmitting.

When Si24R2F+ enables automatic transmission function, internal watchdog and internal RCOSC clock works, internal timer starts timing and the chip works in Sleep state with only 1uA standby current. When internal timer is full, automatic transmission controller loads and transmits the data of NVM automatically. After transmitting data, chip enters Sleep state. The average power consumption of Si24R2F+ is very low, especially suitable for the application system of button cell power supply.

Si24R2F+ is easy to use, and it can automatically load and transmit data without external MCU. NVM memory can store the configuration of registers and data transmitted. The data will not be lost after power failure and can be maintained for more than 10 years. Under the 3.3V power supply voltage, the external MCU can complete the NVM configuration programming through the 4-wire SPI interface of the chip without external high voltage. The maximum programmable number of the chip is 64 times. The chip supports the NVM locked to prevent the NVM configuration data back to read and ensure data security.

Si24R2F+ has very low cost of system application. To design an active RFID wireless



data transmission system, there are a few external passive components and no external MCU needed.



2 Pin Information

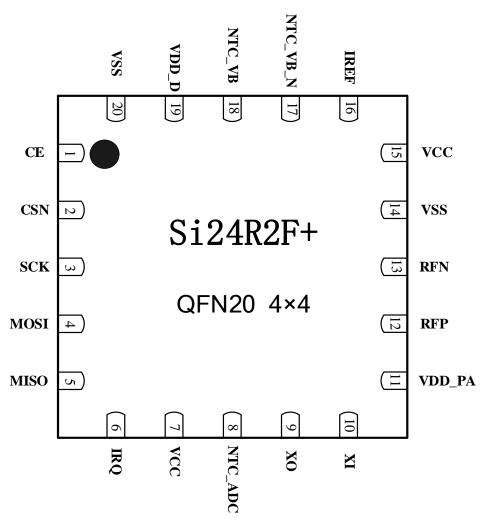


Figure 2-1 Si24R42F+ pin information (QFN20 4×4 package)

Table 2.1 pin function

Pin	Name	Type	Pin function	
1	CE	DI	Turn the chip on, avoid disassembling	
2	CSN	DI	SPI Chip Select	
3	SCK	DI	SPI Clock, use button to transmit, replace the transmission control signal	
4	MOSI	DI	SPI Input, use button to transmit, replace the transmission control signal,	
			edge count	
5	MISO	DO	SPI Output	



6	IRQ	DO	Maskable interrupt pin. Active low	
7	VCC	Power	Power supply $(+1.9 \sim +3.6 \text{V}, \text{ DC})$	
8	NTC_ADC	AO	NTC measurement input	
9	XO	AO	Crystal oscillator output	
10	XI	AI	Crystal oscillator input	
11	VDD_PA	Power	1.8V power supply output for the internal Power Amplifier	
12	RFP	RF	Antenna port 1	
13	RFN	RF	Antenna port 2	
14	VSS	Power	Ground (0V)	
15	VCC	Power	Power supply $(+1.9 \sim +3.6 \text{V}, \text{ DC})$	
16	IREF	AI	Reference current	
17	NTC_VB_N	AO	NTC low voltage output	
18	NTC_VB	AO	NTC high voltage output	
19	VDD_D	РО	Positive Digital Supply output for de-coupling purposes	
20	VSS	Power	Ground (0V)	
	Die exposed	Power	Ground (0V), connect die exposed to PCB ground	



3 Operational modes

3.1 State Control Diagram

The built-in state machine in Si24R2F+ controls the transitions between the chip's different operating modes.

The state transition diagram in Figure 3-1 shows five operating modes of the Si24R2F+. The five operating modes are: Shutdown, Standby, Idle-TX, TX and ATR.

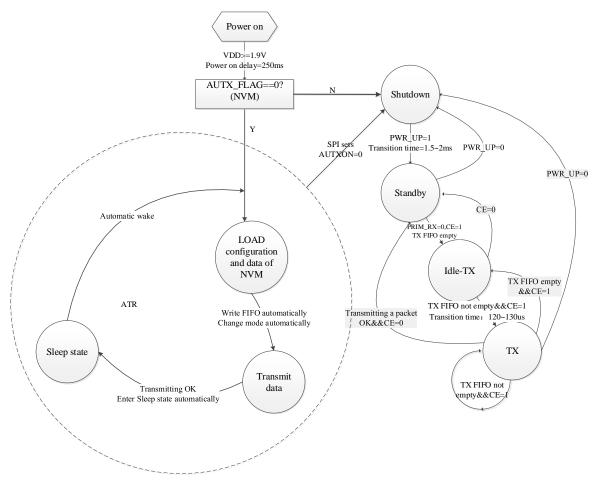


Figure 3-1 Si24R2F+ state control diagram

3.1.1 Shutdown Mode

When NVM makes the function of ATR inactive, AUTX_FLAG is high and the Si24R2F+ enters Shutdown mode directly after power-on. In Shutdown mode, Si24R2F+ is disabled and the current consumption is minimal. All register values available are maintained and can be written or read by SPI which is kept active. The shutdown supply current is 1uA.

Shutdown mode is entered by clearing the PWR_UP bit in the CONFIG register.

3.1.2 Standby Mode

In Standby mode, only part of crystal oscillator is active. Standby mode ensures minimum average current consumption while maintaining short start-up time. Standby mode is entered after the crystal oscillator works stably by setting PWR_UP bit in the CONFIG register to 1. The crystal oscillator startup time is about 1.5~2ms, responding to the oscillator quality. The Si24R2F+ enters Idle-TX mode from Standby mode by setting CE high. When CE pin is set low, Si24R2F+ returns to Standby mode from Idle-TX mode or TX mode.

3.1.3 Idle-TX Mode

In Idle-TX mode, the crystal oscillator and clock buffers are active and more current is used compared to Standby mode. Idle-TX mode is entered when CE is set high and TX FIFO is empty on a PTX device. If a new packet is uploaded to the TX FIFO, the circuit inside the chip will be active immediately, TX mode is entered and the packet is transmitted.

Both in Standby and Idle-TX mode all register and FIFO values available are maintained and can be written or read by SPI.

3.1.4 TX Mode

The TX mode is an active mode for transmitting packets. When the PWR_UP is set high, the PRIM_RX is set low, a payload in the TX FIFO, and a high pulse on the CE pin for more than 10us, the Si24R2F+ enters this mode. Instead of switching directly from the standby mode to the TX mode, Si24R2F+ should switch from the standby mode to Idle-TX mode, and then switch to TX mode. The transition time from Idle-TX mode to TX mode takes 160us. After transmitting a packet, if CE = 1, the status of TX FIFO determines the next mode. If the TX FIFO is not empty, the Si24R2F+ remains in TX mode and transmits the next packet. If the TX FIFO is empty, the Si24R2F+ returns to Idle-TX mode. If CE = 0, the Si24R2F+ returns to Standby mode immediately. The Si24R2F+ provides an interrupt after finishing a packet transmitting.

3.1.5 ATR Mode

When NVM makes the ATR active, AUTX_FLAG is low. When CSN is high, the Si24R2F+ will enter ATR mode after power-on, load the configuration of registers

ČZŅ

Si24R2F+

automatically from NVM and write data to FIFO. Data will be transmitted after the Si24R2F+ works stably, and then Si24R2F+ will enter Sleep state. In Sleep state, internal hardware Watchdog, RCOSC and timer circuit work, all the register values are maintained, the current of the Si24R2F+ is about 1uA. Less time to transmit data and working mostly in Sleep state contribute to low average current consumption.

The retransmission of data can be configured in NVM, allows simple ALOHA protocol and automatic frequency hopping of three frequency points. It reduces the probability of conflict when multiple chips simultaneously transmit data.

When the ATR is active, external MCU writes the AUTX_ON command through SPI interface and then the function of ATR will be inactive. MCU can implement internal register configuration and data transmission through SPI interface. When MCU writes the same AUTX_ON command to reopen ATR, the Si24R2F+ will enter ATR mode. AUTX_ON will be inactive after the software reset command executed or the Si24R2F+ power on, making the ATR active again.

When the ATR is active, the CSN of SPI must be pulled down and then pulled up (low voltage pulse) before external MCU writes the AUTX_ON command through SPI interface. Then CSN will be pulled down to write the AUTX_ON command.

In ATR mode, internal hardware Watchdog can be active automatically. If data is unsuccessfully sent three times in a row, the Si24R2F+ will reset automatically.



4 Packet processing protocol

Si24R2F+ is based on packet communication and uses the same packet format as Si24R1. Internal baseband engine can realize automatic packet handling without an extra MCU. Baseband supports the handling of 1 to 32 bytes dynamic payload length which is inside the packet. Besides, it supports static payload length which is set by registers. Baseband handling features automatic packet disassembly and assembly. It also has 3-stage FIFO for transmitting 3 packets of data at a time.

4.1 Packet format

A whole ARQ packet contains a preamble, address, packet control, payload and CRC field. Figure 4-1 shows the whole packet.



Figure 4-1 A whole ARQ packet

The preamble is used to synchronize the receiver demodulator to the incoming bit stream. It is automatically attached when transmitting and transparent to users.

The address field stores the packet address values for the receiver. A packet will be received only when the address of the packet matches the address of the receiver. The address field width in the AW register can be configured to be 3, 4 or 5 bytes.

Figure 4-2 shows the format of the 9 bit packet control field.

Payload length 6bit	PID 2bit	NO_ACK 1bit
---------------------	----------	-------------

Figure 4-2 Format of packet control field

The 6 bit payload length specifies the length of the payload in bytes ranges from 0 to 32 bytes.

For example: 000000 = 0 byte (no payload) 100000 = 32 byte (32 bytes of payload)

The PID field is used to tell the receiver if the received packet is new or retransmitted. PID prevents the PRX device from receiving the same payload more than once. The PID field is incremented at the PTX device when a new packet is written to FIFO through SPI.

The transmitter doesn't need to receive ACK. When NO_ACK equals 1, the RTX device



doesn't need to send ACK to the PTX device. The payload data field is transmission data content, which can be up to 32 bytes.

The CRC field is the CRC value in the packet. CRC supports either 8 or 16 bits, set by the CRCO bit in the CONFIG register.

4.2 Communication Mode

In the TX mode, the PTX device assembles the preamble, address, packet control field, payload and CRC to make a complete packet first and then it transmits the packet with RF module.

4.2.1 NO ACK Mode

The NO_ACK flag in control field will be set if using W_TX_PAYLOAD_NOACK to command the PTX writing TX PAYLOAD. After sending a packet of data, the PTX will generates TX_DS interrupt immediately, and start to prepare sending next packet of data. After receiving data, the PRX judge the NO_ACK flag setting and the data is valid, then generates RX_DR interrupt. Now a frame of data communication is done and the PRX needn't to transmit an ACK signal.

4.2.2 Dynamic payload length (DPL) and static payload length

A PTX device with DPL enabled must have the EN_DPL bit in FEATURE register and the DPL_P0 bit in DYNPD register set. The first 6 bits in the control field of the packaged data are the length of the data for sending.

The PRX set the EN_DPL bit in FEATURE register, and enable the pipe of DYNPD register. It will receive data according to the length control field. Thus, every time when receiving payload data, its length can be different. MCU can read out the payload length by using R_RX_PL_WID command. If it is static payload length by default, the payload length every time the PTX sending should be the same, and the value should be the same as RX_PW_PX registers set by the receiver.

4.3 Compatibility Mode

Si24R2F+ can provide another packet format, Figure 4-3 shows the whole packet.:

Preamble Address	Payload	CRC
------------------	---------	-----

Figure 4-3 Another packet format

In Compatibility mode, EN_AA should be set low. DPL mode is inactive, DPL_PX and EN_DPL should be set low. The receiver should set RX_PW_PX for PTX sending the length of packet, set DPL_PX and EN_DPL to low. What's more, the data rate can only be set as 1Mbps or 250kbps.

4.4 Bluetooth Mode

Si24R2F+ can send BLE packet (TX payload). Bluetooth packet can be only available in Compatibility mode. A whole packet contains a preamble, address, payload and CRC field, compatible with BLE4.2. The broadcast address is fixed at 0x6B7D9171. The length of packet in bytes ranges from 10 to 40 bytes.

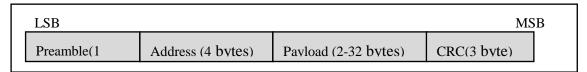


Figure 4-4 Bluetooth packet format

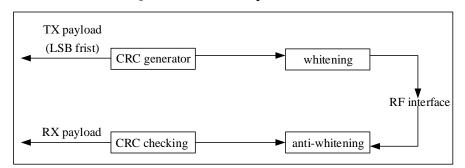


Figure 4-5 BLE packet data stream

BLUE_EN is set high to enable bluetooth function. BLE index can be configured through register BLUE_INDEX .The mapping of the BLE data channel, broadcast channel and RF channel is shown in Table 4-1:

RF channel (N)
RF center frequency Type Data channel index channel index

0~3 2400+N MHz Broadcast channel 37

Table 4-1 The mapping of the BLE data channel and broadcast channel

Data channel

Broadcast channel

Data channel

Broadcast channel 10 39

Data channel (N>>1)-3

0

(N>>1)-2

38

(N>>1)-3

4~25

26~27

28~79

80~81

≥82

2404+N MHz

2400+N MHz

2404+N MHz

2400+N MHz

2404+N MHz



5 SPI Interface

The SPI interface is a standard 4-wire SPI with a maximum data rate of 10 Mbps. MCU can configure the Si24R2F+ through SPI interface, including R/W register, read and write FIFO, read the status of Si24R2F+, clear the interrupts etc.

5.1 SPI Commands

Table 5-1 shows the SPI commands, and every new command must be started by a high to low transition on CSN pin. Every time a SPI operation, the first byte output by MISO is the value of the STATUS register, then the command determines whether to output the value (never output HRS value).

- <Command byte: MSBit to LSBit > -- one byte
- <Data bytes: LSByte to MSByte, MSBbit to LSBbit of every byte first >

For details, please refer to SPI timing, Figure 5-1 & Figure 5-2.

Table 5-1 SPI Commands

Command name	Command word (binary)	# Data bytes	Operation
R_REGISTER	000A AAAA	1 to 5 LSByte first	Read register command. AAAAA= 5 bit Register address (refer to register table)
W_REGISTER	001A AAAA	1 to 5 LSByte first	write register command. AAAAA= 5 bit Register address (refer to register table) Executable in Shutdown、Standby or Idle-TX modes only
FLUSH_TX	1110 0001	0	Flush TX FIFO, used in TX mode
REUSE_TX_PL	1110 0011	0	Used for PTX. The command can't be used after flushing TX FIFO or writing new data to FIFO
W_TX_PAYLOAD_ NO ACK	1011 0000	1 to 32 LSByte first	Used in TX mode. AUTOACK should be set 1 when using this command
SW_RST	01100011	0	Software Reset command, reset the whole Si24R2F+. If NVM is programmed and ATR is active, Si24R2F+ will enter ATR mode after software reset.

AUTX_ON	01011100	1	Write 0x5C command and send 0xA7 to force closing or open ATR function. The command can close ATR and allow MCU to operate register table. The command will fail after hardware or software reset. AUTX_FLAG in NVM determines whether the ATR function is open.
NOP	1111 1111	0	No operation. Can be used to get the value of STATUS register

5.2 SPI Timing

SPI operation includes basic read or write operation and other command operation. Figure 5-1 & Figure 5-2 show the SPI timing.

ATTENTION: The configuration registers can only be written in Shutdown/Standby/Idle-TX mode.

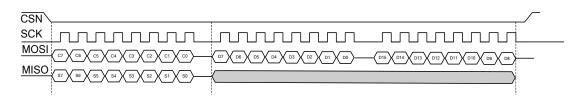


Figure 5-1 SPI write operation

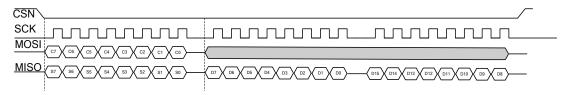


Figure 5-2 SPI read operation

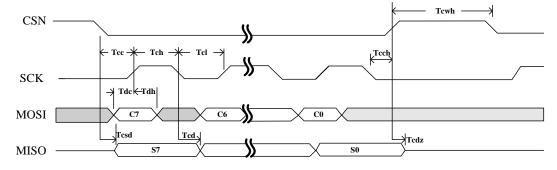


Figure 5-3 SPI typical timing



Table 5-2 shows SPI Interface typical timing parameter

Table 5-2 SPI timing parameter

		<i>U</i> 1		
Symbol	Parameters	Min	Max	Units
Tdc	Data to SCK Setup	2		ns
Tdh	SCK to Data Hold	2		ns
Tcsd	CSN to Data Valid		42	ns
Tcd	SCK to Data Valid		58	ns
Tcl	SCK Low Time	40		ns
Tch	SCK High Time	gh Time 40 n		ns
Fsck	SCK Frequency	0	10	MHz
Tr,Tf	SCK Rise and Fall		100	ns
Tcc	CSN to SCK Setup	2		ns
Tcch	SCK to CSN Hold	2		ns
Tewh	CSN Inactive time	50		ns
Tcdz	CSN to Output High Z	42 ns		ns



6 Register Table

Address (Hex)	Mnemonic	Bit	Reset Value	Type	Description
00	CONFIG				Configuration Register
	BLUE_EN	7	0	R/W	1: enable bluetooth 0: disable bluetooth
	Reserved	6	0	R/W	Reserved, Only '0' allowed
	MASK_TX_DS	5	0	R/W	Mask interrupt caused by TX_DS 1: Interrupt not reflected on the IRQ pin 0: Reflect TX_DS as active low interrupt on the IRQ pin
	Reserved	4	0	R/W	Reserved, only '0' allowed
	EN_CRC	3	1	R/W	Enable CRC. Forced high if one of the bits in the EN_AA is high 0: close CRC 1: open CRC
	CRCO	2	0	R/W	CRC encoding scheme 0:1 byte 1:2 bytes
	PWR_UP	1	0	R/W	Power up/down control 1: POWER UP 0: POWER DOWN
	PRIM_RX	0	0	R/W	0
01	EN_AA				Enable Auto Acknowledgment function
		7:6	00	R	
		5:0	1	R/W	In NOCRC, all bits are low In Compatibility mode, all bits are low, set ARC to 0
02	Reserved	7:0		NA	Reserved, only '0' allowed
03	SETUP_AW				Setup of Address Widths
	Reserved	7:2		R/W	Reserved, only '000000' allowed
	AW	1:0	11	R/W	TX Address field width 00: illegal 01: 3 bytes



					10: 4 bytes
					11: 5 bytes
04	SETUP_RETR				
	Reserved	7:0		NA	Reserved, only '00000000' allowed
05	RF_CH				
	Reserved	7:0	0	R/W	Reserved, only '00000000' allowed
06	RF_SETUP				RF Setup
	CONT_WAVE	7	0	R/W	1: Const carrier wave, for test only
	Reserved	6	0	R/W	Reserved, only '0' allowed
	RF_DR_LOW	5	0	R/W	Set RF data rate to 250kbps . 1Mbps or
	KI'_DK_LOW	3	U	IX/ VV	2Mbps together with RF_DR_HIGH
	PLL_LOCK	4	0	R/W	Reserved, only '0' allowed
					Set RF data rate
					[RF_DR_LOW, RF_DR_HIGH]:
	RF_DR_HIGH	3	1	R/W	00: 1Mbps
	na_ba_mon	3	-	10, 11	01: 2Mbps
					10: 250kbps
					11: reserved
					Set RF output power in TX mode
					111: 12dBm 110: 11.5dBm
	RF_PWR	2:0	110	R/W	101: 9.5dBm 100: 7.5dBm
					011: 4.5dBm 010:1dBm
					001:-2.5dBm 000:-7dBm
07	OFF A FIX C				Status Register (The first byte operated by
07	STATUS				SPI, the STATUS register is shifted serially
	D 1	7.	00	D ATT	out on the MISO pin)
	Reserved	7:6	00	R/W	Reserved, only '00' allowed
					Data sent TX FIFO interrupt
	TV Do	_	_	D //37	Asserted when packet transmitted on TX. If
	TX_DS	5	0	R/W	AUTO_ACK is activated, this bit is set high
					only when ACK is received
	D 1	A	0	D/W	Write '1' to clear bit
	Reserved	2.1	0	R/W	Reserved annu 1111 allowed
	Reserved	3:1	111	R/W	Reserved, only '111' allowed
	TX_FULL	0	0	R	TX FIFO full flag
00	D 1				
08	Reserved				



		7 ^		37.1	D 1
	Reserved	7:0		NA	Reserved
00	D 1				
09	Reserved	. .		27.1	7
	Reserved	7:0		NA	Reserved
0.4	D 1	20.0		27.4	D 1
0A	Reserved	39:8		NA	Reserved
	_	7:0		R	Temperature Register
0B	Reserved	39:0		NA	Reserved
0C	Reserved	7:0		NA	Reserved
0D	Reserved	7:0		NA	Reserved
0E	Reserved	7:0		NA	Reserved
0F	Reserved	7:0		NA	Reserved
					Transmit address. Used for a PTX device
			0xE7E7E		only. (LSB byte is written first) Set
10	TX_ADDR	39:0	7E7E7	R/W	RX_ADDR_P0 equal to this address and
			TETET		enable ARQ if PTX needs to receive ACK
					signal
11	Reserved				
	Reserved	7:0		NA	Reserved
12	Reserved				
	Reserved	7:6		NA	Reserved
		_	- 14 - 4	D	When adc_status is high, temperature read is
		5	adc_status	R	correct
		4:0		NA	Reserved
13	Reserved				
	Reserved	7:0		R/W	Reserved
14	Reserved				
	Reserved	7:0		NA	Reserved
15	Reserved				
	Reserved	7:0		NA	Reserved
16	Reserved				
	Reserved	7:0	00	NA	Reserved
17	FIFO_STATUS				FIFO state
	Reserved	7	0	R/W	Reserved, only '0' allowed
	TX_REUSE	6	0	R	Used for PTX, Reuse last transmitted data
<u> </u>	111_112002				and



					packet by the SPI command REUSE_TX_PL
					and is reset by the SPI command
					W_TX_PAYLOAD or FLUSH_TX
					TX FIFO full flag
	TX_FULL	5	0	R	1: TX FIFO full
					0: TX FIFO not full
					TX FIFO empty flag
	TX_EMPTY	4	1	R	1: TX FIFO empty
					0: TX FIFO not empty
	Reserved	3:0	0000	R/W	Reserved, only '0000' allowed
1C	DYNPD				Enable dynamic payload length
	Reserved	7:1	0		
	DPL_P0	0	0	R/W	1: Enable dynamic payload length
1D	FEATURE			R/W	Feature Register
	Reserved	7:3	0	R/W	Reserved, only '00000' allowed
	EN_DPL	2	0	R/W	Enable dynamic payload length
	Reserved	1:0		NA	Reserved, only '01' allowed



7 Electrical specification

7.1 Limitation parameter

Operating Condition	Min.	Max.	Unit				
Supply Voltages	Supply Voltages						
VDD	-0.3	3.6	V				
VSS		0	V				
Input Voltage							
VI	-0.3	3.6	V				
Output Voltage							
VO	VSS to VDD	VSS to VDD	V				
Power Dissipation							
		100	mW				
Temperatures	Temperatures						
Operation Temperature	-40	+85	$^{\circ}$				
Storage Temperature	-40	+125	$^{\circ}$				
ESD Performance	HBM(Human Body Model): Class 1C						

7.2 Electrical specification

Conditions: VDD = 3V, VSS = 0V , TA = 27 $^{\circ}\text{C}$, crystal oscillator $C_L \!\!=\!\! 12pF$

Symbol	parameter	Min.	Тур.	Max.	Unit	Comment
OP Parameters						
VDD	Supply voltage	2.1		3.6	V	
I_{SHD}	Supply current in Shutdown mode		2		μA	
Isleep	Supply current in Sleep mode		0.7		μA	RCOSC,Watchdog and ATR Timer are active
I _{STB}	Supply current in Standby mode		20		μΑ	
I _{IDLE}	Supply current in Idle-TX mode		380		μΑ	
I _{TX} @12dBm	TX mode supply current @12 dBm output power		41		mA	



TX mode supply current @7.5		26		mA	
dBm output power					
TX mode supply current @1		20		mΔ	
dBm output power		20		ША	
TX mode supply current @-2.5		10		A	
dBm output power		19		IIIA	
TX mode supply current @-7		1.4		mΛ	
dBm output power		14		IIIA	
RF operation frequency	2400		2525	MHz	
DE description	1			MII-	2MHz at least when
RF channel space	1			MHZ	2Mpbs
Frequency deviation		±330		KHz	
F 1 1 2		175		1711	
Frequency deviation		±1/5		KHZ	
Data rate	250		2000	Kbps	
RF Output Power	-7		12	dBm	
Modulation Bandwidth		2.1		MHz	
Modulation Bandwidth		1.1		MHz	
Modulation Bandwidth		0.9		MHz	
1st Adjacent CH Power 2MHz			-20	dBm	
2 nd Adjacent CH Power 4MHz			-46	dBm	
Crystal Oscillator Parameter					
Crystal frequency		16		MHz	
Tolerance		±10		ppm	
Equivalent Series Resistance		100		Ω	
	dBm output power TX mode supply current @1 dBm output power TX mode supply current @-2.5 dBm output power TX mode supply current @-7 dBm output power RF operation frequency RF channel space Frequency deviation Frequency deviation Data rate RF Output Power Modulation Bandwidth Modulation Bandwidth Ist Adjacent CH Power 2MHz 2nd Adjacent CH Power 4MHz Parameter Crystal frequency Tolerance	dBm output power TX mode supply current @1 dBm output power TX mode supply current @-2.5 dBm output power TX mode supply current @-7 dBm output power RF operation frequency 2400 RF channel space 1 Frequency deviation Frequency deviation Data rate 250 RF Output Power -7 Modulation Bandwidth Modulation Bandwidth Ist Adjacent CH Power 2MHz 2nd Adjacent CH Power 4MHz Parameter Crystal frequency Tolerance	### TX mode supply current @1 dBm output power TX mode supply current @-2.5 dBm output power TX mode supply current @-7 dBm output power RF operation frequency 2400 RF channel space 1 Frequency deviation ±330 Frequency deviation ±175 Data rate 250 RF Output Power -7 Modulation Bandwidth 1.1 Modulation Bandwidth 0.9 Ist Adjacent CH Power 2MHz Parameter Crystal frequency 16 Tolerance 10 20 20 20 21 20 21 40 12 14 14 14 15 16 21 20 16 17 20 21 20 21 20 21 21 22 20 24 24 20 24 24 24 26 24 24 24 24 24 24	### TX mode supply current @1 dBm output power TX mode supply current @-2.5 dBm output power TX mode supply current @-2.5 dBm output power TX mode supply current @-7 dBm output power ### RF operation frequency ### RF operation frequency ### Prequency deviation ###	Max Max



8 Package

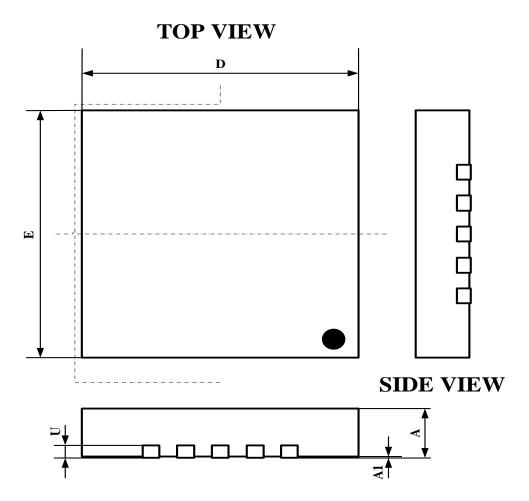


Figure 8-1 Top view



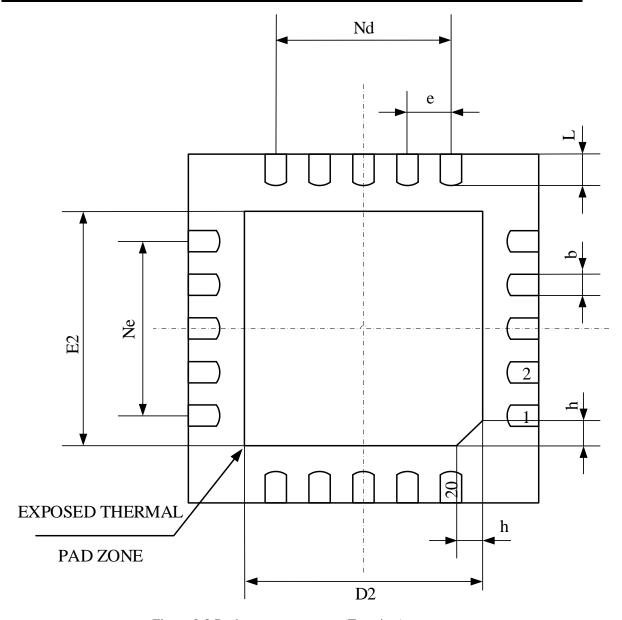


Figure 8-2 Package measurement (Top view)

SYMBOL	MILLIMETER				
	MIN	NOM	MAX		
A	0.70	0.75	0.80		
A1		0.02	0.05		
b	0.18	0.25	0.30		
D	3.90	4.00	4.10		
D2	2.55	2.65	2.75		
e	0.50BSC				
E2	2.55	2.65	2.75		



Е	3.90	4.00	4.10	
Ne	2.00BSC			
Nd	2.00BSC			
L	0.35	0.40	0.45	
h	0.30 0.35 0.40			
U	0.20 REF.			
L/F (mil)	114×114			



9 Typical Application Schematic

9.1 Typical Application Schematic

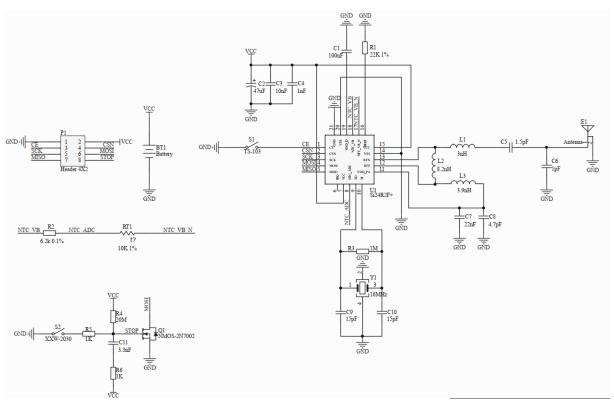


Figure 9-1 Typical application schematic

Table 9-1 Recommended components (BOM)

Designator	Part	Footprint	Description
C1	100nF	0603(1608)	+/- 10%
C2	47uF	1210C+	+/- 10%
C3	10nF	0603(1608)	+/- 10%
C4	1nF	0603(1608)	+/- 5%
C5	1.5pF	0603(1608)	+/- 0.1pF
C6	1pF	0603(1608)	+/- 0.25pF
C7	22nF	0603(1608)	+/- 10%
C8	4.7pF	0603(1608)	+/- 0.25pF
С9	15pF	0603(1608)	+/- 5%
C10	15pF	0603(1608)	+/- 5%
C11	3.3nF	0603(1608)	+/- 10%



L1	3nH	0603(1608)	+/- 10%
L2	8.2nH	0603(1608)	+/- 5%
L3	3.9nH	0603(1608)	+/- 5%
R1	22ΚΩ	0603(1608)	+/- 1%
R2	6.2ΚΩ	0603(1608)	+/- 0.1%
R3	1MΩ	0603(1608)	+/- 1%
R4	20ΜΩ	0603(1608)	+/- 5%
R5	1ΚΩ	0603(1608)	+/- 1%
R6	1ΚΩ	0603(1608)	+/- 1%
RT1	10ΚΩ	HDR1X2	+/- 1%
Y1	16MHz		+/-10ppm, CL=9pF
U1		QFN20 04×04	

9.2 PCB layout

As shown in the figure below is the PCB layout example for the typical application schematic above. A double-sided FR-4 board is used. There is a copper clad surface on the top and bottom layers respectively, the copper clad surfaces of the top and bottom layers are connected by a large number of vias, and there is no copper clad surface under the antenna. The bottom layer of PCB is the ground plane. To achieve better RF performance, the IC substrate die ground (die attach) should connect to PCB ground plane. It is strongly recommended to keep it connected. 47uF tantalum capacitance stays near the battery. The problem that button battery pulse discharge current is insufficient can be solved by more than 4dBm transmission power. Due to long wire routing of VCC, 104 capacitance should be connected near VCC to enhance the ability of electrostatic protection.



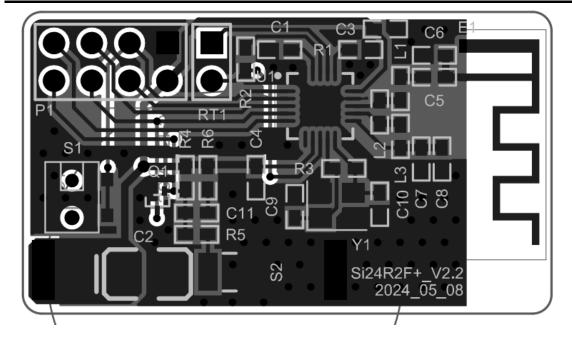


Figure 9-2 PCB layout



10 Version Information

Version	Modified date	Modified content
V0.1	2023/11/13	First draft
V0.2	2024/04/29	Modify Typical Application Schematic, PCB layout and the value of C1
V0.3	2024/05/08	Modify Typical Application Schematic, PCB layout and the value of C7
		and L3



11 Order Information

Package marking

Si24R2F+ ABBCDEE

Si24R2F+: chip code

A: package date code, 5 represents year 2020

BB: week of sending out processing, 42 represents in the year A the 42th week

C: package factory code, A, HT, NJ or WA, can also abbreviated as A, H, N or W

D: test factory code, A, Z or H

EE: production batch code

Table 11-1 Si24R2F+ order example

order code	package	container	minimum
Si24R2F+-Sample	4×4mm 20-pin QFN	Box/Tube	5
Si24R2F+	4×4mm 20-pin QFN	Tape and reel	4K



12 Technical Support and Contact Information

Nanjing Zhongke Microelectronic Industry Technology Research Institute Co., Ltd

Technical Support Center

Phone: 025-68517780

Address: Room 201, Building B, Research Zone 3, Xuzhuang Software Park, Xuanwu District, Nanjing,

Jiangsu, China

Website: http://www.csm-ic.com

Sales and Marketing

Phone: 13645157034, 13645157035

Email: sales@csmic.ac.cn

Technical Support Phone: 13645157034

Email: supports@csmic.ac.cn



Appendix - Top machine screenshot

